



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-07-07
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STISO621WTR	1J3J*U1PDADA	A	Z4DA	2020-07-07
	Amount	UoM	Unit type	ST ECOPACK Grade
	241	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Package Size	Nbr of instances	Shape	
D50	7.4932.655.842	8	Gull wing	
Comment	A03J SO 8 WIDE 300			

QueryList : RoHS Directive 2011/65/EU-July 2011 Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	Description

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product

QueryList : REACH-25th June 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update				
Query				Response
The Product does contain at least one of the substances listed in Chemical Control Act				false
Substance	Homogeneous Material impacted	Content in Homogeneous Material (mg)	Concentration in the material(%)	Application Purpose

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	1131*U1PDADA			699999.0	1000001.0	
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	1.081	mg	supplier	die	Silicon(Si)	7440-21-3		1.024	mg	947271	4257
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.011	mg	10176	46
				supplier	metallisation	Chromium(Cr)	7440-47-3		0.001	mg	925	4
				supplier	metallisation	Gold(Au)	7440-57-5		0.002	mg	1850	8
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.004	mg	3700	17
				supplier	metallisation	Tungsten(W)	7440-33-7		0.008	mg	7401	33
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.002	mg	1850	8
				supplier	passivation	Silicon oxide	7631-86-9		0.018	mg	16651	75
				supplier	polymer coating	polyimide	proprietary		0.011	mg	10176	46
				Leadframe	M-004 Copper and its alloys	33.672	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8	
supplier	alloy & coating	Iron(Fe)	7439-89-6						0.800	mg	23759	3326
supplier	alloy & coating	Phosphorus metal	7723-14-0						0.010	mg	297	42
supplier	alloy & coating	Zinc(Zn)	7440-66-6						0.050	mg	1485	208
supplier	alloy & coating	Silver (Ag)	7440-22-4						0.220	mg	6534	915
supplier	glue	Silver	7440-22-4						0.106	mg	762590	441
Die attach	M-011 Other inorganic materials	0.139	mg	supplier	glue	Acrylic resin	Proprietary		0.011	mg	79137	46
				supplier	glue	Acrylate	Proprietary		0.007	mg	50360	29
				supplier	glue	Butadiene copolymer	Proprietary		0.001	mg	7194	4
				supplier	glue	Polybutadiene derivative	Proprietary		0.007	mg	50360	29
				supplier	glue	Epoxy Resin	Proprietary		0.005	mg	35971	21
				supplier	glue	Peroxide	Proprietary		0.001	mg	7194	4
				supplier	glue	Additive	Proprietary		0.001	mg	7194	4
				supplier	glue	Silver	7440-22-4		0.104	mg	770370	432
Die attach 2	M-011 Other inorganic materials	0.135	mg	supplier	glue	Acrylic resin	Proprietary		0.011	mg	81481	46
				supplier	glue	Acrylate	Proprietary		0.007	mg	51852	29
				supplier	glue	Butadiene copolymer	Proprietary		0.001	mg	7407	4
				supplier	glue	Polybutadiene derivative	Proprietary		0.007	mg	51852	29
				supplier	glue	Epoxy Resin	Proprietary		0.003	mg	22222	12
				supplier	glue	Peroxide	Proprietary		0.001	mg	7407	4
				supplier	glue	Additive	Proprietary		0.001	mg	7407	4
				supplier	wire	Au	7440-57-5		0.253	mg	1000000	1052
Bonding wires	M-008 Precious metals	0.253	mg	supplier	wire	Au	7440-57-5		0.253	mg	1000000	1052
				supplier	mold compound	Epoxy Resin A	proprietary		3.060	mg	14957	12721
				supplier	mold compound	Epoxy Resin B	proprietary		3.060	mg	14957	12721
				supplier	mold compound	Phenol Resin	proprietary		13.700	mg	66964	56954
				supplier	mold compound	Silica(Amorphous) A	60676-86-0		163.000	mg	796727	677622
				supplier	mold compound	Silica(Amorphous) B	7631-86-9		20.367	mg	99552	84670
Encapsulation	M-011 Other inorganic materials	204.587	mg	supplier	mold compound	Carbon black	1333-86-4		1.400	mg	6843	5820
				supplier	mold compound	Tin (Sn)	7440-31-5		0.680	mg	1000000	2827
connections coating	Solder	0.680	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.680	mg	1000000	2827